

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("6679759").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:44
L2	405635	wafer wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:44
L3	318473	polishing polish polished polishes	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:44
L4	38584	slicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:44
L5	602	I2 with I3 with I4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:44
L6	683	silicon adj block	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:44
L7	4	I5 and I6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:47
L8	602	I5 with I3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:48

L9	602	I8 and I4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:48
L10	67	I9 and ("125"/\$.ccls. "451"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 12:48
L11	17	("4084354").URPN.	USPAT	OR	OFF	2005/04/25 12:50
L12	5227	(silicon semiconductor substrate) adj (boule ingot block)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 13:08
L13	252	I12 with I3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 13:08
L14	8248166	side sides	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 13:08
L15	28	I13 with I14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 13:09
L16	224	I13 not I15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/25 13:09